GLOBALFOUNDRIES Achieves 14nm FinFET Technology Success for Next-Generation AMD Products

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Leading-edge foundry's proven silicon technology poised to help enable significant performance and power efficiency improvements for AMD's next-generation products

Santa Clara, Calif., November 5, 2015 -- GLOBALFOUNDRIES today announced it has demonstrated silicon success on the first AMD (NASDAQ: AMD) products using GF's most advanced 14nm FinFET process technology. As a result of this milestone, GF's silicon-proven technology is planned to be integrated into multiple AMD products that address the growing need for high-performance, power-efficient compute and graphics technologies across a broad set of applications, from personal computers to data centers to immersive computing devices.

AMD has taped out multiple products using GF's 14nm Low Power Plus (14LPP) process technology and is currently conducting validation work on 14LPP production samples. Today's announcement represents another significant milestone towards reaching full production readiness of GF's 14LPP process technology, which will reach high-volume production in 2016. The 14LPP platform taps the benefits of three-dimensional, fully-depleted FinFET transistors to enable customers like AMD to deliver more processing power in a smaller footprint for applications that demand the ultimate in performance.

"FinFET technology is expected to play a critical foundational role across multiple AMD product lines, starting in 2016," said Mark Papermaster, senior vice president and chief technology officer at AMD. "GF has worked tirelessly to reach this key milestone on its 14LPP process. We look forward to GF' continued progress towards full production readiness and expect to leverage the advanced 14LPP process technology across a broad set of our CPU, APU, and GPU products."

"Our 14nm FinFET technology is among the most advanced in the industry, offering an ideal solution for demanding high-volume, high-performance, and power-efficient designs with the best die size," said Mike Cadigan, senior vice president of product management at GF. "Through our close design-technology partnership with AMD, we can help them deliver products with a performance boost over 28nm technology, while maintaining a superior power footprint and providing a true cost advantage due to significant area scaling."

GF's 14LPP FinFET is ramping with production-ready yields and excellent model-to-hardware correlation at its Fab 8 facility in New York. In January, the early-access version of the technology (14LPE) was successfully qualified for volume production, while achieving yield targets on lead customer products. The performance-enhanced version of the technology (14LPP) was qualified in the third quarter of 2015, with the early ramp occurring in the fourth quarter of 2015 and full-scale production set for 2016.

ABOUT GF

GF is the world's first full-service semiconductor foundry with a truly global footprint. Launched in March 2009, the company has quickly achieved scale as one of the largest foundries in the world, providing a unique combination of advanced technology and manufacturing to more than 250 customers. With operations in Singapore, Germany and the United States, GF is the only foundry that offers the flexibility and security of manufacturing centers spanning three continents. The company's 300mm fabs and 200mm fabs provide the full range of process technologies from mainstream to the leading edge. This global manufacturing footprint is supported by major facilities for research, development and design enablement located near hubs of semiconductor activity in the United States, Europe and Asia. GF is owned by Mubadala Development Company. For more information, visit http://www.globalfoundries.com.

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